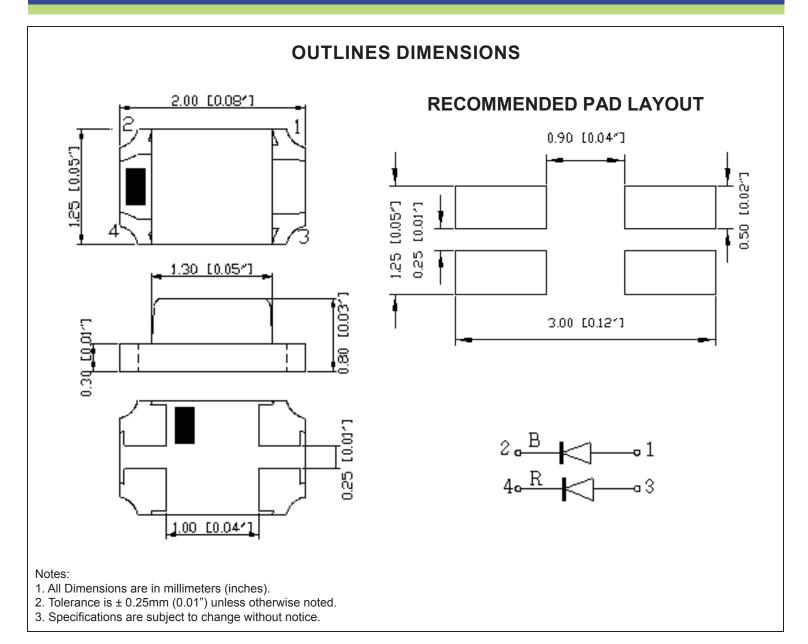


# SPECIFICATIONS CSB85BR2B2C



Part Number	Chip Material	Color of Emission Lens Type Viewing		Viewing Angle
CSB85BR2B2C	InGaAlP/InGaN	Red/Blue	Water Clear	140°





## **ABSOLUTE MAXIMUM RATINGS**

(TA=25°C)

Parameter	Symbol	Color	Max Rating	Unit			
Power Discipation	PD	RED	75	mW			
Power Dissipation	PD	BLUE	111				
Pulse Current Forward Current	lFP	RED	125	mA			
Fulse Current Forward Current	IFP	BLUE	125	IIIA			
Continuous Forward Current	lF	RED	30	mA			
Continuous Forward Current		BLUE	30	IIIA			
Reverse Voltage	VR	5		V			
Operating Temperature Range	Topr	-40~+80		°C			
Storage Temperature Range	Тѕтс	-40~+85		°C			
IFP = Pulse Width ≤ 10 ms, Duty Rat	= Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec						

## **OPTICAL-ELECTRICAL CHARACTERISTICS**

(TA=25°C)

Doromotor	Symbol	Test Condi- tion	Color	Value			Linit
Parameter				Min	Тур	Max	Unit
Luminous Intonsity	lv	I <sub>F</sub> = 20mA	Red	50	100	-	mcd
Luminous Intensity			Blue	50	85	-	
Converd Voltage	VF	I <sub>F</sub> = 20mA	RED	-	2.0	2.5	V
Forward Voltage			Blue	-	3.1	3.7	
Doverna Lankaga Current	lR	V <sub>R</sub> = 5V	RED	-	ı	10	μA
Reverse Leakage Current			Blue	-	-	10	
Viouing Angle	2θ1/2	I <sub>F</sub> = 20mA	RED	-	140	-	deg
/iewing Angle			Blue	-	140	-	
Dominant Wavelength	λD	I <sub>F</sub> = 20mA	RED	625	630	635	nm
			Blue	465	470	475	

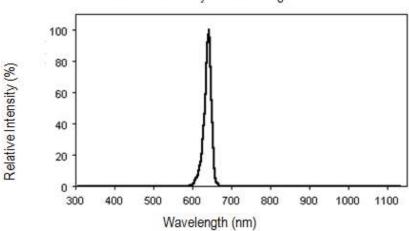
<sup>\*</sup>Tolerance of viewing angle: -10 / +5 deg.



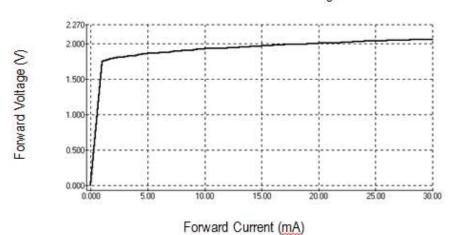


# **OPTICAL CHARACTERISTIC CURVES (RED)**

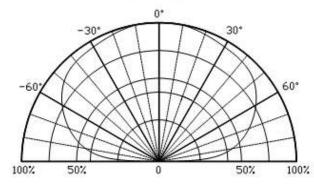
### Relative Intensity vs. Wavelength



### Forward Current vs. Forward Voltage



### Directive Characteristics

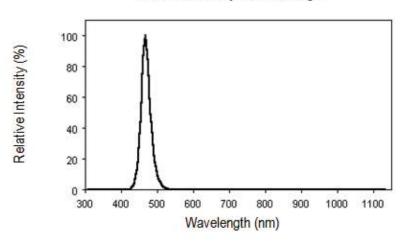


RoHS Compliant

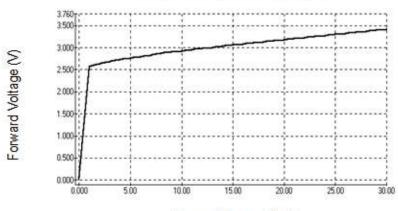


# **OPTICAL CHARACTERISTIC CURVES (BLUE)**

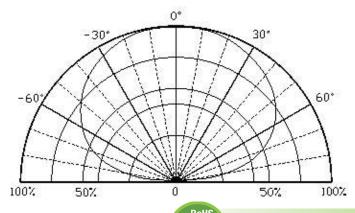
### Relative Intensity vs. Wavelength



### Forward Current vs. Forward Voltage



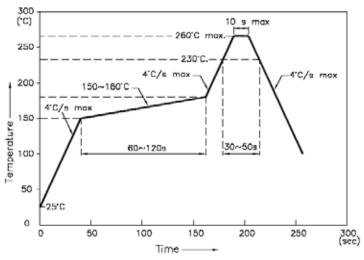
### Forward Current (mA)





## **SOLDERING CONDITIONS**

### **Reflow Profile/Time**

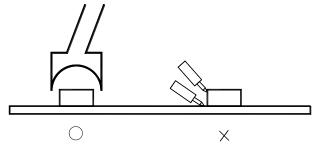


#### NOTES:

- 1. We recommend the reflow temperature 245°C (±5°C).the maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- Number of reflow process shall be 2 times or less.
  - Soldering iron
  - Basic spec is ≤ 5sec when 260°C. If temperature is higher, time should be shorter
  - (+10°C → -1sec ). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable . Surface temperature of the device should be under 230°C .

#### Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil
- 3. Twin-head type is preferred.

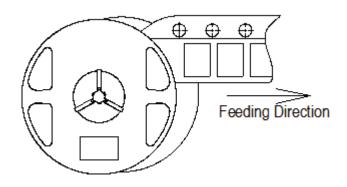




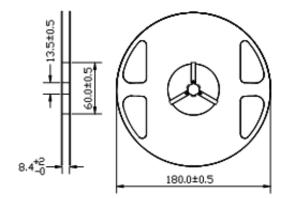


## **PACKAGING SPECIFICATIONS**

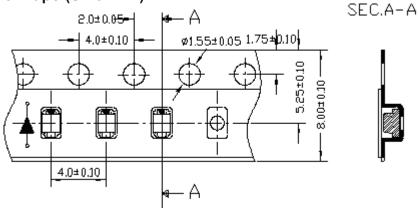
### • Feeding Direction



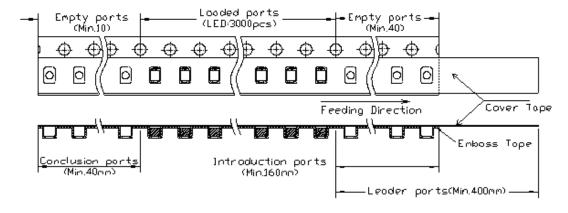
## Dimensions of Reel (Unit: mm)



### Dimensions of Tape (Unit: mm)



### Arrangement of Tape



#### Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 3,000pcs/Reel

